

WaferBond 2019 EAST

2019 6th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2019)

May 21–25, 2019 Kanazawa
Ishikawa-prefecture, Japan

Abstract Due

January 11, 2019



Photo: Kanazawa City

Sponsored by

191st Committee on Innovative Interface Bonding Technology,
Japan Society for the Promotion of Science (JSPS)

Co-sponsored by

IEEE EPS Japan Chapter
Institute for Advanced Micro-System Integration (IMSI)
The Japan Society of Applied Physics



2019 6th International Workshop on Low Temperature Bonding for 3D Integration (LTB-3D 2019) will be held from 21-25, May 2019 at Kanazawa-city, Japan.

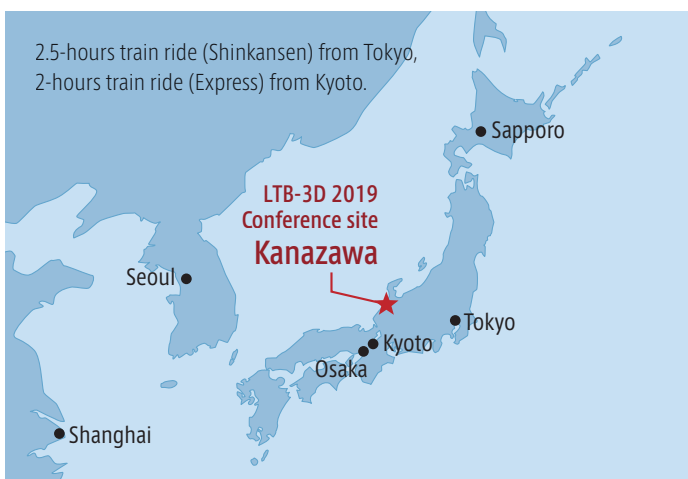
The LTB-3D is a premier conference series sponsored by the 191st Committee on Innovative Interface Bonding Technology, Japan Society for the Promotion of Science (JSPS), and cosponsored by the IEEE EPS Japan Chapter, preceding 1st (2007), 2nd (2010), 3rd (2012), 4th (2014), and 5th (2017) in Tokyo, and in coming 2019, moving to an attractive old city, Kanazawa, as WaferBond 2019 EAST in conjunction with WaferBond conferences which are held in Europe every two years: 2009 (Grenoble), 2011 (Chemnitz), 2013 (Stockholm), 2015 (Braunschweig), and 2017 (Leuven) .

This workshop is focusing on the promotion of advanced research areas related to low-temperature bonding technologies, including surface activated bonding (SAB), which realize novel device structure by heterogeneous material and device integration and lead to entirely new manufacturing approaches to 3D and module integration of semiconductor devices, photonics systems, and power electronic systems. These bonding technologies have been already used for the volume production and have potential applications in wide range of manufacturing industries. It has been attracting over 200 attendees with participants from more than 20 countries and regions worldwide. This workshop will be held as a single-track seminar to provide comprehensive information on the latest technologies and applications, as well as business opportunities.

Professor Dr. Tadatomo Suga

The University of Tokyo
191st Committee on Innovative Interface Bonding Technology, JSPS
IEEE EPS Japan Chapter

2.5-hours train ride (Shinkansen) from Tokyo,
2-hours train ride (Express) from Kyoto.



Venue

Kanazawa, Ishikawa-prefecture, Japan

- 21st Century Museum of Contemporary Art (Welcome reception)
- Kanazawa Castle Park (Conference reception)
- Ishikawa Prefectural Noh Theater (General session)
- Kanazawa Tokyu Hotel (General session, Exhibition)



Ishikawa Prefectural Noh Theater



21st Century Museum of Contemporary Art

Conference date

- May 21, 2019 — Welcome reception
- May 22 & 24, 2019 — General sessions
- May 22, 2019 — Conference reception
- May 23, 2019 — General sessions & Exhibition
- May 25, 2019 — Post conference meetings

Conference scope

- 3D & Hetero Integration
- Wafer Bonding
- Surface Activated Bonding (SAB) and its Extensions
- Hydrophilic & Plasma-assist Bonding
- III-V & Photonics Integration
- Low-Temperature Bonding and Applications
- Bonding and Debonding for High-Temperature Applications
- Bonding for Power Module Integration
- Bonding for Polymer and Glass Device Integration
- Bonding Diamond and Carbon Materials
- Bonding for Biosensing Device Integration
- MEMS and Optoelectronic System Integration
- Bonding for Nano-Micro System
- Bonding Thermoelectric Materials
- Bonding High-Temperature Superconductors
- Bonding Interface Reliability
- Equipments and Quality Assessment

Important date

- Abstract submission deadline — **January 11th, 2019**
- Acceptance/Rejection notification — **February 18th, 2019**
- Final manuscript and presentation materials deadline — **March 18th, 2019**
- Conference — **May 21st-25th, 2019**

For further information, visit:

<http://www.jsps191.org/ltb3d-2019/>